

(0.635 mm) .025"

**MIS SERIES** 

# MIXED TECHNOLOGY SOCKET

# **SPECIFICATIONS**

For complete specifications and recommended PCB layouts see www.samtec.com?MIS

Insulator Material:

Liquid Crystal Polymer Contact Material: Phosphor Bronze

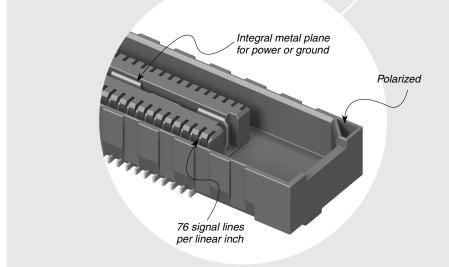
Phosphol Biolize
Plating:
Au or Sn over
50 µ" (1.27 µm) Ni
Operating Temp Range:
-55 °C to +125 °C
Voltage Rating:

Max Cycles:

**RoHS Compliant:** 

## **Board Mates:**

Standoffs:



#### **PROCESSING**

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (019-057) Board Stacking:

For applications requiring more than two connectors per board contact ipg@samtec.com

# **RECOGNITIONS**

For complete scope of recognitions see www.samtec.com/quality



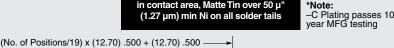
## ALSO AVAILABLE (MOQ Required)

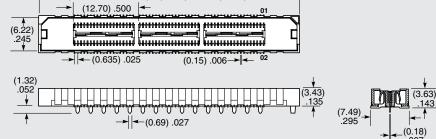
- 11 mm, 16 mm, 18.75 mm and 22 mm stack height
- 30 μ" (0.76 μm) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 76, 95, 114 and 133 positions per row

# **POSITIONS PLATING** MIS OPTION **PER ROW OPTION** -019, -038, -057 (38 total positions per bank) = Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails = 10 μ" (0.25 μm) Gold on Signal Pins and Ground Plane, Matte Tin on tails -C\*= Electro-Polished Selective 50 μ" (1.27 μm) min Au over 150 μ" (3.81 μm) Ni on Signal Pins in contact area, 10 μ" (0.25 μm) min Au over 50 μ" (1.27 μm) Ni on Ground Plane in contact area, Matte Tin over 50 μ" \*Note:



**PACKAGING** 





**Note:** Rugged through-hole ground plane soldered to board (requires paste-over-hole, not press-fit) for added retention to PCB.

**MATED HEIGHT\*** MIT LEAD STYLE -02 (5.00) (8.00) .197 .315

\*Processing conditions will affect mated height. See SO Series for board space tolerances.

Some lengths, styles and options are non-standard, non-returnable.